

ABSTRACT OF THE DISCLOSURE

METHOD AND APPARATUS FOR PROCESSING WAFER-SHAPED ARTICLES

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A method and device for processing wafer-shaped articles includes a spin chuck for holding and rotating a wafer-shaped article about a rotation axis, and at least one dispenser for dispensing a fluid onto at least one surface
10 of a wafer-shaped article. A collector surrounds the spin chuck for collecting process fluids, with at least two collector levels for separately collecting fluids in different collector levels. Each collector level comprises an exhaust gas collecting chamber leading to a respective
15 exhaust gas conduit. At least one of the exhaust gas conduits comprises a valve mechanism that reciprocally restricts exhaust gas flow from its associated exhaust gas conduit while opening the exhaust gas conduit to an ambient environment outside the collector, and vice-versa.

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FIG. 1

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